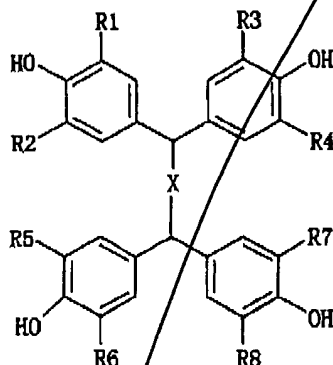


CLEAN VERSION OF CLAIMS 2 AND 3

ENTER.

2. (Twice Amended) A clathrate curing accelerator for epoxy resins comprising:  
a tetrakisphenol compound represented by a general formula [I];

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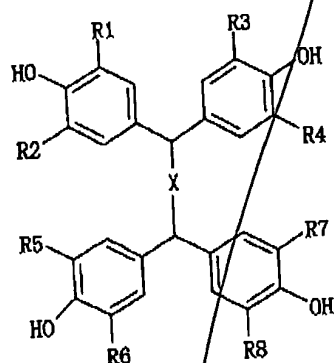


wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which accelerates the curing of an epoxy resin, wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

3. (Twice Amended) Epoxy resin compositions comprising:

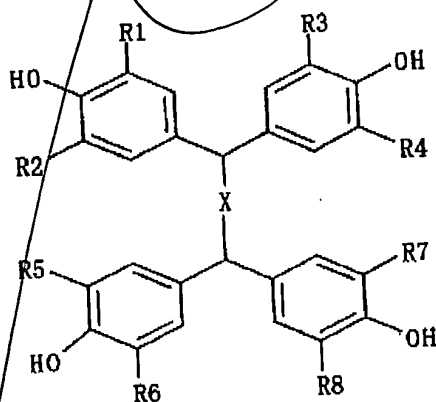
an epoxy resin, said epoxy resin containing  
an epoxy resin, said epoxy resin containing a clathrate curative,  
said clathrate curative being a tetrakisphenol compound  
represented by a general formula [I]



wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which reacts with epoxy groups of the epoxy resin to cure the resin, wherein the clathrate curative is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups; and/or

a clathrate curing accelerator, said clathrate curing accelerator being a tetrakisphenol compound represented by a



wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

64 a compound other than the tetrakisphenol compound, which accelerates the curing of an epoxy resin, wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

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